



Material Content Data Sheet



Sales Product Name	TLE9833QX			Issued		28. August 2013		
MA#	MA000985218							
Package	PG-VQFN-48-29			Weight*		130.22 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.983	3.83	3.83	38268	38268
leadframe	inorganic material	phosphorus	7723-14-0	0.018	0.01		138	
	non noble metal	zinc	7440-66-6	0.072	0.06		550	
	non noble metal	iron	7439-89-6	1.433	1.10		11006	
	non noble metal	copper	7440-50-8	58.193	44.68	45.85	446885	458579
wire	noble metal	gold	7440-57-5	0.782	0.60	0.60	6009	6009
encapsulation	organic material	carbon black	1333-86-4	0.181	0.14		1389	
	plastics	epoxy resin	-	7.656	5.88		58792	
	inorganic material	silicondioxide	60676-86-0	52.446	40.28	46.30	402751	462932
leadfinish	non noble metal	tin	7440-31-5	2.596	1.99	1.99	19939	19939
plating	noble metal	silver	7440-22-4	0.614	0.47	0.47	4714	4714
glue	plastics	epoxy resin	-	0.286	0.22		2199	
	noble metal	silver	7440-22-4	0.958	0.74	0.96	7360	9559
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

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